

## JAPANESE PATENT OFFICE

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## SEMICONDUCTOR DEVICE

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[There are no amendments to this patent.]

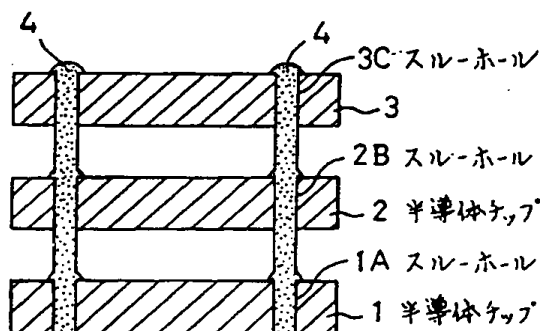
## Abstract

### Purpose

To realize an integrated circuit with high mounting density by stacking multiple semiconductor chips.

### Constitution

Multiple semiconductor chips 1, 2, 3 are stacked at specific intervals and are electrically connected by means of conductive material 4 through through-holes 1A, 2B, 3C provided to the semiconductor chips.



Key: 1     Semiconductor chip  
       1A    Through-holes  
       2     Semiconductor chip  
       2B    Through-holes  
       3C    Through-holes

Claim

A semiconductor device characterized in that multiple semiconductor chips having multiple through-holes are stacked at specific intervals by means of a conductive material in the through-holes, and said semiconductor chips are electrically connected.

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